



#### 1.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

#### **Features**

- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automated Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 30A Peak
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- Lead Free Finish/RoHS Compliant (Note 1)
- Green Molding Compound (No Halogen and Antimony) (Note 2)

# **Mechanical Data**

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Marking Information: See page 3
- Ordering Information: See page 3
- Weight: SMA 0.064 grams (approximate)
  SMB 0.093 grams (approximate)





Top View

**Bottom View** 

## **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	B120/B	B130/B	B140/B	B150/B	B160/B	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	20	30	40	50	60	<b>V</b>
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	21	28	35	42	V
Average Rectified Output Current @ T <sub>T</sub> = 130°C	lo			1.0			Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>			30			Α

### **Thermal Characteristics**

Characteristic	Symbol	B120/B	B130/B	B140/B	B150/B	B160/B	Unit
Typical Thermal Resistance Junction to Terminal (Note 3)	$R_{\theta JT}$			20			°C/W
Operating and Storage Temperature Range	T <sub>J.</sub> T <sub>STG</sub>			-65 to +150	)		°C

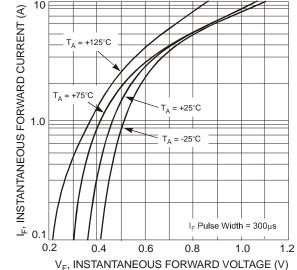
## **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Chara	cteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	B120/B, B130/B, B140/B B150/B, B160/B	\/-	-	-	0.5 0.7	V	I <sub>F</sub> = 1.0A I <sub>F</sub> = 1.0A
Leakage Current (Note 4)		I <sub>R</sub>	-	-	0.5 10	mA	@ Rated V <sub>R</sub> , T <sub>A</sub> = 25°C @ Rated V <sub>R</sub> , T <sub>A</sub> = 100°C
Total Capacitance		Ст	-	-	110	pF	$V_R = 4V, f = 1MHz$

Notes:

- 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at http://www.diodes.com/quality/lead\_free.html.
- 2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
- 3. Thermal Resistance: Junction to terminal, unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink.
- 4. Short duration pulse test used to minimize self-heating effect.





 $V_{\rm F}$ , INSTANTANEOUS FORWARD VOLTAGE (V) Fig. 1 Typical Forward Characteristics - B120/B thru B140/B

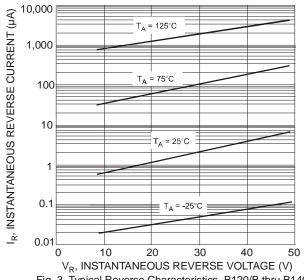


Fig. 3 Typical Reverse Characteristics, B120/B thru B140/B

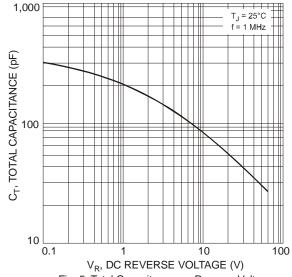


Fig. 5 Total Capacitance vs. Reverse Voltage

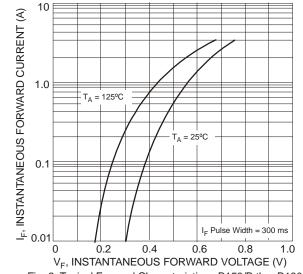


Fig. 2 Typical Forward Characteristics - B150/B thru B160/B

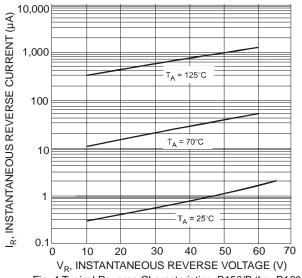
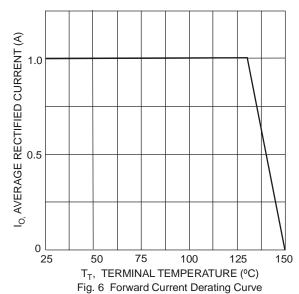


Fig. 4 Typical Reverse Characteristics, B150/B thru B160/B





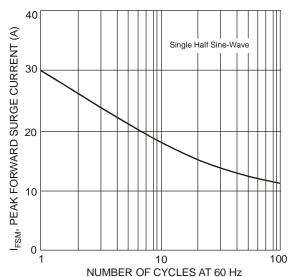


Fig. 7 Max Non-Repetitive Peak Forward Surge Current

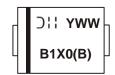
# Ordering Information (Note 5)

Part Number	Case	Packaging
B1XX-13-F	SMA	5000/Tape & Reel
B1XXB-13-F	SMB	3000/Tape & Reel

<sup>\*</sup>xx = Device Type, e.g. B120-13-F (SMA Package); B120B-13-F (SMB Package).

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Marking Information**

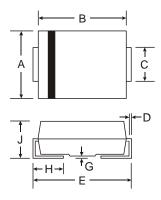


B1X0 = Product type marking code, ex: B120 (SMA package) B1X0B = Product type marking code, ex: B160B (SMB package)

>!! = Manufacturers' code marking YWW = Date code marking Y = Last digit of year (ex: 2 for 2002)

WW = Week code 01 to 52

# **Package Outline Dimensions**

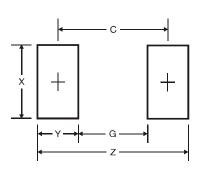


SMA				
Dim	Min	Max		
Α	2.29	2.92		
В	4.00	4.60		
C	1.27	1.63		
D	0.15	0.31		
Е	4.80	5.59		
<b>G</b> 0.05 0.20				
<b>H</b> 0.76 1.52				
7	2.01	2.30		
All Dimensions in mm				

SMB				
Dim	Min	Max		
Α	3.30	3.94		
В	4.06	4.57		
C	1.96	2.21		
D	0.15	0.31		
Е	5.00	5.59		
G	0.05	0.20		
Η	0.76	1.52		
7	2.00	2.62		
All Dimensions in mm				



### **Suggested Pad Layout**



SMA Dimensions	Value (in mm)
Z	6.5
G	1.5
Х	1.7
Υ	2.5
С	4.0

SMB Dimensions	Value (in mm)
Z	6.7
G	1.8
Х	2.3
Υ	2.5
С	4.3

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